

#### MOS FIELD EFFECT TRANSISTOR

### NP40N055CHE, NP40N055DHE, NP40N055EHE

## SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

These products are N-channel MOS Field Effect Transistor designed for high current switching applications.

#### **FEATURES**

- Channel temperature 175 degree rated
- Super low on-state resistance
- $\bigstar$  RDS(on) = 23 m $\Omega$  MAX. (VGS = 10 V, ID = 20 A)
- ★ Low Ciss : Ciss = 1070 pF TYP.
  - Built-in gate protection diode

#### **ORDERING INFORMATION**

PART NUMBER	PACKAGE
NP40N055CHE	TO-220AB
NP40N055DHE	TO-262
NP40N055EHE	TO-263

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	Drain to Source Voltage	Voss	55	V
	Gate to Source Voltage	Vgss	±20	V
	Drain Current (DC)	ID(DC)	±40	Α
	Drain Current (Pulse) Note1	D(pulse)	±160	Α
	Total Power Dissipation (T <sub>A</sub> = 25°C)	Р⊤	1.8	W
*	Total Power Dissipation (Tc = 25°C)	$P_T$	66	W
*	Single Avalanche Current Note2	las	29 / 21 / 7	Α
*	Single Avalanche Energy Note2	Eas	0.8 / 44 / 49	mJ
	Channel Temperature	$T_ch$	175	°C
	Storage Temperature	$T_{stg}$	-55 to +175	°C

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1 %

**2.** Starting T<sub>ch</sub> = 25°C, R<sub>G</sub> = 25  $\Omega$  , V<sub>GS</sub> = 20 V $\rightarrow$ 0 V

#### THERMAL RESISTANCE

*	★ Channel to Case	Rth(ch-C)	2.27	°C/W	
	Channel to Ambient	Rth(ch-A)	83.3	°C/W	

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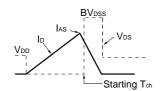


#### **\*** ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

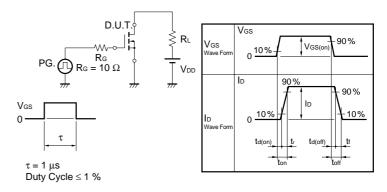
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)	Vgs = 10 V, lp = 20 A		18	23	mΩ
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	2.0	3.0	4.0	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A	7	14		S
Drain Leakage Current	loss	V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate to Source Leakage Current	Igss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V		1070	1610	pF
Output Capacitance	Coss	V <sub>G</sub> s = 0 V		190	280	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		95	180	pF
Turn-on Delay Time	td(on)	ID = 20 A		35	77	ns
Rise Time	tr	V <sub>GS(on)</sub> = 10 V		440	1090	ns
Turn-off Delay Time	<b>t</b> d(off)	V <sub>DD</sub> = 28 V		55	110	ns
Fall Time	t <sub>f</sub>	$R_G = 10 \Omega$		82	210	ns
Total Gate Charge	Q <sub>G</sub>	ID = 40 A		23	35	nC
Gate to Source Charge	Qgs	$V_{DD} = 44 V$ $V_{GS} = 10 V$		6		nC
Gate to Drain Charge	Q <sub>GD</sub>			9		nC
Body Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 40 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 40 A, VGS = 0 V		38		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		46		nC

#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{Rg} = 25 \ \Omega \\ \text{VGS} = 20 \rightarrow 0 \ V \end{array} \begin{array}{c} \text{PG.} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{$\downarrow$} \\ \text{$\downarrow$} \\ \text{$\downarrow$} \end{array} \begin{array}{c} \text{Vob} \\ \text{$\downarrow$} \end{array}$



#### **TEST CIRCUIT 2 SWITCHING TIME**



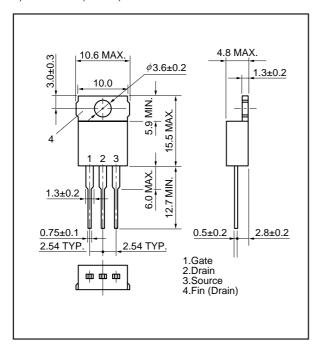
#### **TEST CIRCUIT 3 GATE CHARGE**

$$\begin{array}{c|c} D.U.T. \\ \hline I_G = 2 \text{ mA} \\ \hline WV \\ \hline \end{array} \begin{array}{c} I_T \\ \hline I_T \\ \hline \end{array} \begin{array}{c} RL \\ \hline \end{array}$$

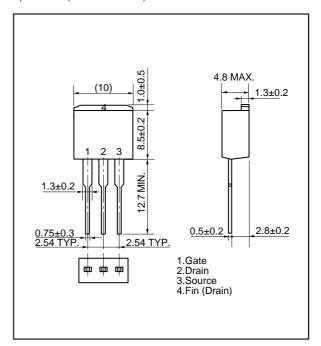


#### PACKAGE DRAWINGS (Unit: mm)

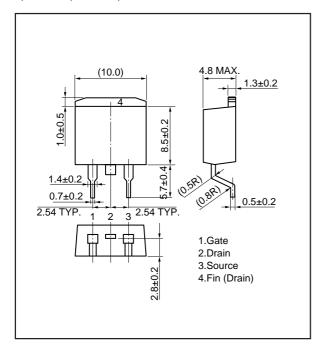
#### 1) TO-220AB (MP-25)



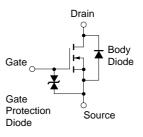
#### 2) TO-262 (MP-25 Fin Cut)



#### 3) TO-263 (MP-25ZJ)



#### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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